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(54) High-frequency module

(57) There is described a high-frequency module comprising a high-frequency device-mounting package and an external circuit board characterized in that said high-frequency device-mounting package (A) includes a dielectric substrate (1) having a first grounding layer (4) contained therein, said dielectric substrate (1) mounting a high-frequency device (2) on one surface thereof and having, formed on one surface thereof, first high-frequency signal transmission lines (3) connected to said high-frequency device (2), and having, formed on the other surface thereof, second high-frequency signal transmission lines (7) coupled to said first high-frequency signal transmission lines (3), said external circuit board (B) is constituted by a dielectric board (20) having third high-frequency signal transmission lines (25) and a second grounding layer (26), said third high-frequency signal transmission lines (25) being formed on one surface of said dielectric board (20), and said second grounding layer (26) being formed on the other surface of said dielectric board (20) or inside thereof; and said high-frequency device-mounting package (A) and said external circuit board (B) are arranged side by side, and the second high-frequency signal transmission lines (7) of the high-frequency device-mounting package (A) are electrically connected to the third high-frequency signal transmission lines (25) of the external circuit board (B) through linear electrically conducting members (31). The patterns of the second high-frequency signal transmission lines on the side of the high-frequency device-mounting package can be easily aligned with the patterns of the third high-frequency signal transmission lines on the side of the external circuit board, effectively reducing the transmission loss at the junction portions of the lines.

EP 0 977 298 A3

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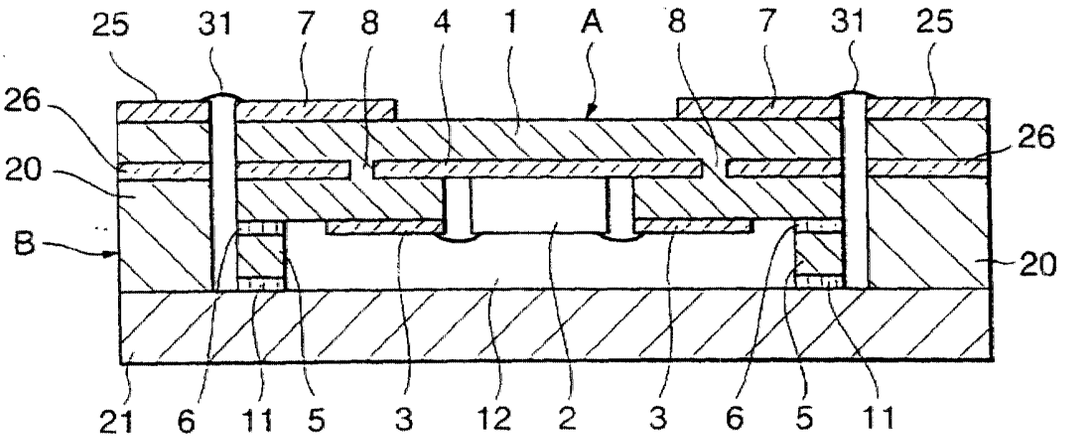
FIG. 1



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EUROPEAN SEARCH REPORT

Application Number
EP 99 11 4940

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Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.7)
Y	PATENT ABSTRACTS OF JAPAN vol. 017, no. 344 (E-1390), 29 June 1993 (1993-06-29) & JP 05 048239 A (FUTABA CORP), 26 February 1993 (1993-02-26) * abstract * ---	1-4,19	H01P1/04
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A	US 4 827 327 A (MIYAUCHI ET AL.) 2 May 1989 (1989-05-02) * column 3, line 37 - column 4, line 56; figure 1 * -----	1,3,19	

TECHNICAL FIELDS SEARCHED (Int.Cl.7)

H01P
H05K
H01L

The present search report has been drawn up for all claims

Place of search	Date of completion of the search	Examiner
THE HAGUE	30 August 2001	Den Otter, A

CATEGORY OF CITED DOCUMENTS

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For more details about this annex : see Official Journal of the European Patent Office, No. 12/82